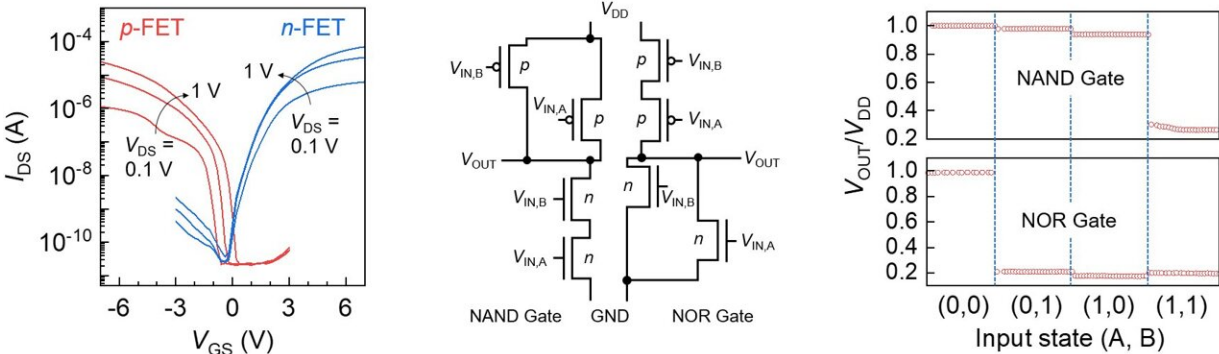


New ultra-thin electrode material gets us a step closer to next-generation semiconductors

May 30 2022



Operation results of the two-dimensional semiconductor device and logic device implemented by the joint research team. Credit: Korea Institute of Science and Technology (KIST)

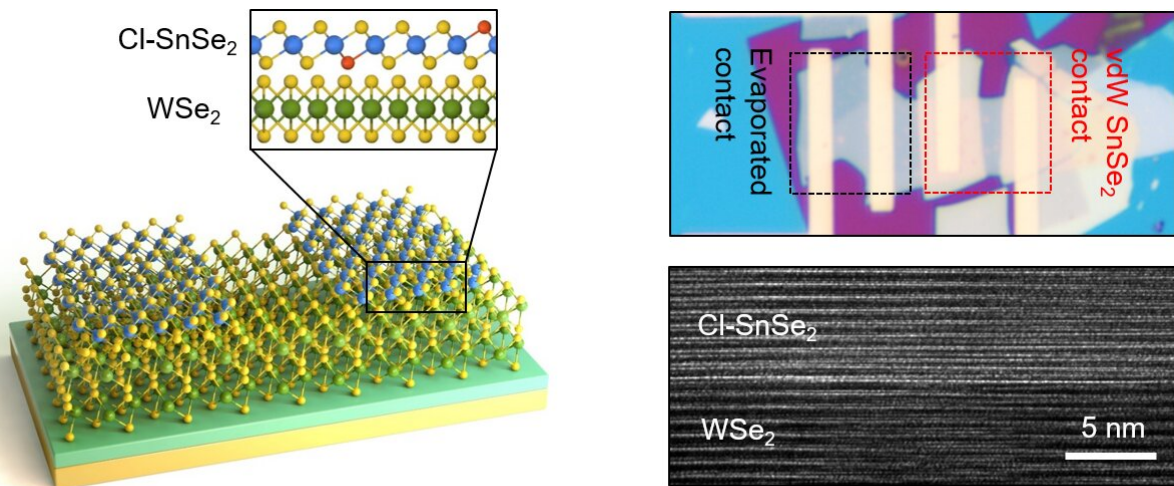
To realize artificial intelligence systems and autonomous driving systems, processors must be able to handle more data. However, silicon-based logic devices have limitations in that processing costs and power consumption increase as miniaturization and integration progress.

To overcome these limitations, researchers are studying electronic and [logic devices](#) based on thin, two-dimensional semiconductors at an atomic layer level. However, it is more difficult to control the electrical properties through doping in two-dimensional semiconductors than in conventional silicon-based semiconductor devices. Thus, it has been

technically difficult to implement logic devices with two-dimensional semiconductors.

The (KIST; President: Seok-jin Yoon) announced that a joint research team at the Korea Institute of Science and Technology, led by Dr. Do Kyung Hwang of the Center for Opto-Electronic Materials and Devices and Professor Kimoon Lee of the Department of Physics at Kunsan National University, has implemented two-dimensional, semiconductor-based electronic and logic devices with [electrical properties](#) that can be controlled via a new ultra-thin electrode material (Cl-SnSe₂).

It was difficult to implement complementary logic circuits with conventional two-dimensional semiconductor devices because they only exhibit the characteristics of either N-type or P-type devices due to the Fermi-level pinning phenomenon. In contrast, the new electrode material makes it possible to freely control the characteristics of the N-type and P-type devices by minimizing defects with the semiconductor interface. In other words, a single device performs the functions of both N-type and P-type devices. Hence, there is no need to manufacture the N-type and P-type devices separately. By using this device, the joint research team successfully implemented a high-performance, [low-power](#), complementary logic circuit that can perform logic operations such as NOR and NAND.



Structure of the two-dimensional semiconductor electronic device implemented in this study (left) and its image captured through an electron microscope (right). Credit: Korea Institute of Science and Technology (KIST)

Dr. Hwang said, "This development will contribute to accelerating the commercialization of next-generation system technologies such as [artificial intelligence systems](#), which have been difficult to use in practical applications due to technical limitations caused by the miniaturization and high integration of conventional silicon semiconductor devices. The developed two-dimensional electrode material is very thin; hence, it exhibits high light transmittance and flexibility. Therefore, it can be used for next-generation flexible and transparent [semiconductor devices](#)."

The study is published in *Advanced Materials*.

More information: Jisu Jang et al, Fermi-Level Pinning-Free WSe₂ Transistors via 2D Van der Waals Metal Contacts and Their Circuits, *Advanced Materials* (2022). [DOI: 10.1002/adma.202109899](https://doi.org/10.1002/adma.202109899)

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